



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-14
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD Champions
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	22AA*MV97ABA	A	MA1A	2017-06-14
Amount	UoM	Unit type	ST ECOPACK Grade	
6.0	mg	Each	ECOPACK® 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



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Package Designator	Size	Nbr of instances	Shape	
LGA	2x 2x0.7	12	No lead	
Comment	Package: A069 LGA2X2X0.7 12 LEADS; MDF valid for LIS2MDLTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : REACH-12th January 2017

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	22AA*MV97ABA									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	0.579	mg	supplier	die	Silicon (Si)	7440-21-3		0.502	mg	867012	83667				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.008	mg	13817	1333				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.005	mg	8636	833				
				supplier	metallisation	Iron (Fe)	7439-89-6		0.020	mg	34542	3333				
				supplier	metallisation	Nickel (Ni)	7440-02-0		0.022	mg	37997	3667				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.005	mg	8636	833				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.001	mg	1727	167				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.005	mg	8636	833				
				supplier	passivation	Silicon Oxide	7631-86-9		0.011	mg	18998	1833				
				substrate	Other Organic Materials	1.416	mg	supplier	core material	Fiber glass	65997-17-3		0.211	mg	149060	35167
								supplier	core material	Bisphenol F type epoxy resin	9003-36-5		0.118	mg	83361	19667
								supplier	core material	Bismaleimide (B)	105391-33-1		0.072	mg	50864	12000
supplier	core material	Triazine (T)	25722-66-1						0.072	mg	50864	12000				
supplier	core material	metal hydroxide	21645-51-2						0.005	mg	3532	833				
supplier	core material	Zinc hydroxide	20427-58-1						0.001	mg	706	167				
supplier	core material	Calcium sulfate	7778-18-9						0.002	mg	1413	333				
supplier	Solder mask	Barium sulfate	7727-43-7						0.012	mg	8477	2000				
supplier	Solder mask	Acrylic resin	9003-01-4						0.018	mg	12716	3000				
supplier	Solder mask	Epoxy resin	29690-82-2						0.014	mg	9890	2333				
supplier	Solder mask	Biphenyl epoxy resin	85954-11-6						0.009	mg	6358	1500				
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.007	mg	4945	1167				
supplier	Solder mask	Methoxymethylethoxy propanol	34590-94-8						0.002	mg	1413	333				
supplier	Solder mask	Amorphous silica	7631-86-9						0.001	mg	706	167				
supplier	Solder mask	3-methyl-methoxy-butyl	103429-90-9						0.001	mg	706	167				
supplier	Solder mask	Silica Cristobalite	14464-46-1						0.001	mg	706	167				
supplier	metallisation	Copper (Cu)	7440-50-8						0.859	mg	606735	143143				
supplier	metallisation	Nickel (Ni)	7440-02-0						0.008	mg	5934	1400				
Precious metals	Precious metals			supplier	metallisation	Gold (Au)	7440-57-5		0.001	mg	805	190				
Precious metals	Precious metals			supplier	metallisation	Palladium (Pd)	7440-05-3		0.001	mg	805	190				
Die attach	Other inorganic materials	0.319	mg	supplier	tape	epoxy resin	25068-38-6		0.202	mg	633229	33667				
				supplier	tape	polyolefin	9003-07-0		0.101	mg	316614	16833				
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.016	mg	50157	2667				
Bonding wire	Precious metals	0.118	mg	supplier	wire	Gold (Au)	7440-57-5		0.117	mg	991525	19500				
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	8475	167				
encapsulation	Other Organic Materials	3.568	mg	supplier	mold compound	Silica, vitreous	60676-86-0		2.836	mg	794843	472667				
				supplier	mold compound	Silica	7631-86-9		0.357	mg	100056	59500				
				supplier	mold compound	Epoxy Resin	Proprietary		0.143	mg	40078	23833				
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.125	mg	35034	20833				
				supplier	mold compound	Phenol Resin	Proprietary		0.089	mg	24944	14833				
				supplier	mold compound	Carbon black	1333-86-4		0.018	mg	5045	3000				